



EV077334201

#32
105
N. Chapman
8-28-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References- - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the references listed on the attached Form PTO-1449. No admission is made regarding whether the submitted references are prior art.

Citation of these references is respectfully requested.

RECEIVED

AUG 26 2002

Respectfully submitted,

TECHNOLOGY CENTER R3700

Date: Aug. 19, 2002

Frederick M. Fliegel, Ph.D.
Reg. No. 36,138
Wells St. John P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828
(509) 624-4276

08/22/2002 CNGUYEN 00000008 09148723

01 FC:126

180.00 OP